ISSUE 20 – OCTOBER 2026

NEWS FROM the EIPC

To all EIPC Members,

We are pleased to invite you to our EIPC Members Networking Lunch on Thursday, November 12 from 12:30 to 13:30 hrs on the EIPC stand at Electronica A2-643.

This informal lunch is a great opportunity to meet fellow EIPC members, exchange ideas and experiences, and strengthen your connections within the PCB community. Whether you are a long-standing EIPC member or have recently joined, we would be delighted to welcome you.

Over a relaxed sandwich lunch, you can connect with professionals from different parts of the PCB industry and discover opportunities for cooperation, exchange of knowledge, and future business relationships. It is also an excellent opportunity to meet and speak with the EIPC team in person, share your thoughts, and let us know how EIPC can continue to support you and your company.

We believe that some of the most valuable connections start with a simple conversation over lunch. So, take a break from the busy exhibition floor and join us for an hour of networking, good conversation and informal exchange.

Date: Thursday, November 12, 2026

Time: 12:30–13:30 hrs

Where: Electronica, EIPC stand A2-643

Lunch: Sandwich lunch will be provided

Who: EIPC members and EIPC staff

We look forward to welcoming you and making this a valuable and enjoyable networking moment for our EIPC community.

Please join us and make the most of your EIPC membership!

EIPC Team

Are you joining our networking lunch?

Let us know and send an email to eipc@eipc.org

ISSUE 20 – OCTOBER 2026

NEWS FROM AUSTRIA

AT&S announced repayment of its EUR 350 million 2022 hybrid bond at par on 22 October 2026 from existing cash, refinanced by a 2026 hybrid convertible bond carrying a coupon around 50% lower

October 22, 2026 AT&S

Refinancing significantly reduces ongoing financing costs and optimizes capital structure
Leoben - AT&S will repay the outstanding hybrid bond 2022 (ISIN XS2432941693) with a nominal value of EUR 350 million on 22 October 2026 on the first possible call date. Repayment will be made at par plus accrued interest. The bond is then withdrawn and cancelled.

The redemption follows the successful placement of the Hybrid Convertible Bond 2026. With this refinancing, AT&S is significantly reducing its ongoing financing costs. The coupon of the new financing is around 50% lower than that of the 2022 hybrid bond. This will improve the company's long-term financing profile in the long term.

The repayment will be made from existing cash and cash equivalents and underlines AT&S's solid liquidity and financing position.

"With the repayment at the first possible termination date, we are consistently continuing to optimize our capital structure," says CFO Gerrit Steen. "It is also an expression of AT&S's significantly improved liquidity position. In addition, the successful refinancing significantly reduces our ongoing financing costs and strengthens AT&S's financial flexibility."

AT&S Austria Technologie & Systemtechnik Aktiengesellschaft - Advanced Technologies & Solutions
AT&S is a global technology company and the world's leading supplier of high-quality IC substrates and complex printed circuit boards. The company develops and produces innovative connectivity solutions for key digital industries: AI infrastructure, high-performance computing, mobile devices, automotive, aerospace, industrial and medical technology. With production sites in Austria (Leoben, Fehring), China (Shanghai, Chongqing), Malaysia (Kulim) and India (Nanjangud) as well as a European competence center for R&D and IC substrate production in Leoben, AT&S is actively shaping the digital transformation - through forward-looking investments in research and development as well as the responsible use of resources. The company currently employs about 15,000 people.

ISSUE 20 – OCTOBER 2026

NEWS FROM GERMANY

EMSNOW and in4ma Release Inaugural EMS & ODM Global 100 Market Research Report

Landmark research provides comprehensive analysis of the global electronics manufacturing industry, representing a market exceeding $1 trillion. Report available free of charge thanks to the generous support of industry sponsors.

Southlake, Texas U.S. and Königswinter, Germany, October 2026: in4ma Market Research, a recognized specialist in electronics manufacturing market intelligence, and EMSNOW, a leading global source of news, analysis, and insights for the electronics manufacturing industry, are pleased to announce the release of the inaugural *EMS & ODM Global 100 Market Research Report*.

Developed through a research partnership between EMSNOW and in4ma, this landmark publication provides an in-depth examination of the global Electronics Manufacturing Services (EMS) & Original Design Manufacturing (ODM) industries, including market size, company rankings, regional performance, industry structure, and emerging trends.

Building on the successful launch of the EMS & ODM Global 100 rankings earlier this year, the report represents a significant step forward in providing the industry with comprehensive, independent, and data-driven market intelligence.

A Comprehensive View of a $1 Trillion Global Industry

Based on extensive research and analysis of 2025 industry performance, the report estimates the combined global EMS & ODM market at approximately US$1.007 trillion, highlighting the enormous scale and importance of outsourced electronics manufacturing to the global economy.

The report provides detailed analysis across several key areas:

- **Global market size and growth:** Assessment of the worldwide EMS and ODM market, including Total Addressable Market (TAM) and Serviceable Available Market (SAM).
- **Global 100 company rankings:** Analysis of the world's leading EMS & ODM companies.
- **Regional market dynamics:** Examination of industry performance across Asia, Europe, North America, and other manufacturing regions.

- **Industry structure and market concentration:** Insights into the distribution of revenues among the largest manufacturers and the broader global EMS & ODM community.

The research combines in4ma's extensive company-level financial and market analysis with EMSNOW's global industry reach, editorial expertise, and relationships throughout the electronics manufacturing community.

A Partnership Committed to Better Industry Intelligence

"The EMS & ODM industry has become one of the most important segments of the global electronics ecosystem, yet comprehensive and reliable information about its size, structure, and performance has historically been difficult to obtain," said Eric Miscoll, Publisher of EMSNOW.

"Our partnership with in4ma brings together exceptional research capabilities and a global media platform to address that need. Our objective is not simply to publish another ranking, but to provide meaningful intelligence that helps industry executives, suppliers, customers, and investors better understand the market and make more informed decisions."

Dieter Weiss of in4ma Market Research emphasized the importance of rigorous research and consistent industry definitions. "The global EMS and ODM market is considerably larger and more complex than many traditional industry assessments suggest. Our research extends well beyond the largest publicly traded companies to include private manufacturers and smaller regional providers, giving us a much more complete picture of the industry," said Weiss.

"By combining detailed company-level research with a consistent methodology, we are able to provide a more accurate assessment of the industry's true size, regional distribution, and growth dynamics. Working with EMSNOW allows us to bring these findings to a much broader global audience."

Making Industry Research Available to Everyone

In a departure from the traditional model of expensive subscription-based market research, EMSNOW and in4ma are making the entire inaugural report available free of charge to the global electronics manufacturing community.

This initiative has been made possible through the generous financial support of a distinguished group of industry sponsors who recognize the value of making high-quality market intelligence widely accessible.

"From the outset, we believed this research should be available to everyone in the industry, not just organizations with substantial research budgets," added Miscoll. "Thanks to the generous support of our sponsors, we are able to make that vision a reality. We sincerely appreciate their commitment to supporting greater transparency, understanding, and knowledge throughout the global electronics manufacturing community."

The report is intended to become an important reference for EMS & ODM executives, OEMs, component and equipment suppliers, investors, financial analysts, and other industry stakeholders.

Establishing a New Industry Benchmark

The inaugural EMS & ODM Global 100 Market Research Report establishes a foundation for ongoing analysis of the industry's performance and evolution.

EMSNOW and in4ma plan to continue updating the Global 100 rankings and expanding their research to provide the industry with timely, consistent, and meaningful market intelligence. The next edition of this report is planned for spring 2027.

"We see this report as the beginning of a long-term initiative," said Weiss. "Our goal is to establish a trusted, independent source of research that provides greater visibility into this dynamic and increasingly important global industry."

The inaugural EMS & ODM Global 100 Market Research Report is available now for free download.

Download the report: https://www.flipsnack.com/BB9BB87A9F7/the-emsodm-global-100-report-2026-10_16_2pdf

About EMSNOW
EMSNOW is a leading global media platform dedicated to the electronics manufacturing industry. Through daily news coverage, executive interviews, podcasts, webinars, original research, and industry reports, EMSNOW connects electronics manufacturing professionals worldwide with timely information, insights, and analysis.
www.emsnow.com

About in4ma Market Research
in4ma Market Research specializes in market intelligence and financial analysis of the global Electronics Manufacturing Services (EMS) and Original Design Manufacturing (ODM) industries. Led by industry analyst Dieter Weiss, in4ma provides detailed company-level research, market assessments, and analysis of industry trends, helping manufacturers, suppliers, and investors better understand the global electronics manufacturing landscape.
www.in4ma.de

Media Contact
Eric Miscoll
Publisher, EMSNOW
emiscoll@emsnow.com

ISSUE 20 – OCTOBER 2026

NEWS FROM POLAND

Evertiq Expo Warsaw drew a record 180 exhibitors to its twelfth edition at PGE Narodowy on 22 October, with 1124 attendees, including 635 visitors from 430 companies

October 23, 2026
Evertiq

On Thursday, 22 October, the electronics industry gathered at PGE Narodowy Stadium for the twelfth edition of Evertiq Expo Warsaw. The event has always been known for its international character, but this year it felt, more than ever, like the capital of Europe's electronics industry. The event was preceded by a networking dinner, where lively discussions about the state of the industry set the tone for the day ahead. And there was plenty to look forward to.

The market analyses from Jacek Malecki (Best Supply), Dieter G. Weiss and Anna Zurek-Kasiewicz (in4ma), Riku Hynninen (Agame) and Ewelina Bednarz (Evertiq) had attracted considerable interest. The technical programme, covering technologies, design and the challenges industry professionals face in their everyday work, was just as eagerly awaited.

The following morning, PGE Narodowy opened its doors to visitors, with a record 180 exhibitors ready to welcome them. A total of 1124 people attended, including 635 visitors from 430 different companies and 589 representatives of exhibiting companies.

This year, Evertiq broadened its visitor outreach, with the aim of reaching companies and people who had not attended before, and the difference was noticeable. Alongside Polish participants, the Expo welcomed representatives of the electronics industry from across Europe, Asia and the Arab world. Between them, they covered almost the entire electronics value chain, from semiconductor and component design through manufacturing and distribution to electronics assembly, system integration and finished technology solutions.

From early in the morning, conversations filled the exhibition hall, and many of them were clearly about business. Discussions touched on the growing importance of the defence sector and advances in artificial intelligence and robotics, but also on challenges that have occupied the industry for years. Component availability, shifting supply chains and the need to adapt manufacturing to new conditions remain part of everyday life for many companies. And although the conversations covered different technologies, markets and applications, they had one thing in common: the search

for practical solutions and partners to work with.

"Evertiq's mission is to make the world a better place through electronics. With every event, we want to reach new companies and people who have a real influence on the industry's development. But it is not simply about numbers. What matters most to us is the value we can offer our participants. We believe that in electronics, very few things are impossible. Sometimes, finding the right partner or technology is all it takes to turn even the most ambitious project into reality. And that is exactly what we want Evertiq Expo to make possible," says Irma Bjorsell, CEO of Evertiq.

Warsaw was the final stop on the Evertiq Expo calendar for 2026, and the event returns on 21 October 2027. Next year opens with a premiere: on 29 January, Evertiq Expo comes to Austria for the first time, in Vienna, followed by Grenoble, France, on 4 March.

NEWS FROM GERMANY

Schweizer Electronic moved its shares from the regulated market to the Frankfurt Stock Exchange Scale segment for smaller companies from 30 September 2026 to cut regulatory and administrative costs

September 29, 2026
Schweizer Electronic

Schramberg, 29 September 2026 - Shares in Schweizer Electronic AG (ISIN: DE0005156236, WKN: 515623) will be traded on the Scale segment of the Frankfurt Stock Exchange from 30 September 2026. The company is thus completing the transition from the regulated market to the Scale segment of the open market, as announced on 13 August 2026.
The steps required for the segment change have been completed as planned. The last trading day for the shares of Schweizer Electronic AG on the regulated market of the Frankfurt Stock Exchange (General Standard) and on the regulated market of the Stuttgart Stock Exchange is 29 September 2026. From 30 September 2026, the shares will be listed on the Scale segment of the Frankfurt Stock Exchange.
The tradability of SCHWEIZER shares will remain fully guaranteed throughout the segment change. The shares will continue to be tradable via Xetra and other trading venues.
By moving to Scale, Schweizer Electronic AG is aligning its stock market listing with the company's size and capital market orientation. Scale is a segment of the Open Market (Freiverkehr) of the Frankfurt Stock Exchange with additional transparency requirements and is aimed in particular at small and medium-sized enterprises.
As previously announced in an ad hoc announcement dated 13 August 2026, Schweizer Electronic AG's aim in changing segments is to reduce the regulatory and administrative burden associated with listing on the regulated market, including the associated costs, whilst maintaining its presence on the capital market.
The company will continue to provide shareholders, investors and other capital market participants with regular and transparent updates on the company's performance.
ion and quoting across its printed circuit board plants in China, Thailand and Italy.

STARTEAM GLOBAL has joined IPAI (Innovation Park Artificial Intelligence), an AI innovation hub based in Heilbronn, Germany, to collaborate on the practical application of AI across industries. Based in Heilbronn, Germany, IPAI brings together businesses, researchers, technology providers, and innovators to share knowledge, exchange ideas, and explore real-world AI applications that are shaping the future of industry through a hub of innovational excellence.

With over 35 years of PCB manufacturing expertise and production facilities in China, Thailand, and Italy, STARTEAM GLOBAL is committed to continuously improving quality, efficiency, and customer service through innovation. As the manufacturing landscape evolves, the company sees AI as an important tool for improving efficiency, supporting better decision-making, and creating greater value for its customers.

AI is already a strategic pillar of the company's operations. Through its collaboration with PAILOT, STARTEAM GLOBAL utilises advanced production scheduling technology to optimise manufacturing planning and resource allocation. The company also uses Luminovo's automated quotation platform to streamline the RFQ process and improve responsiveness for its customers, a significant time saver in its made to order industry.

Looking Ahead, STARTEAM GLOBAL is Interested in AI Applications Such As:

AI manufacturing and process optimisation

Automated visual inspection for enhanced quality control

AI-powered technical support for employee onboarding and knowledge transfer

These technologies enhance process consistency, strengthen quality assurance, and accelerate learning throughout the organisation.

"AI will fundamentally transform the way companies operate, but no organisation can drive this transformation alone. By joining IPAI, we want to collaborate with leading innovators, contribute our practical experience in digital transformation, and accelerate the adoption of AI that creates measurable value for our customers, employees, and partners." - Rico Knapper, Chief People and Transformation Officer.

By joining IPAI, the company gains access to a network of AI experts, industrial companies, researchers, and technology innovators. Through this platform, exchange knowledge, learn from proven use cases, and explore practical applications that can further strengthen its manufacturing capabilities.

Most importantly, the company's focus on AI and continuous innovation reflects its commitment to further enhancing quality, responsiveness, operational efficiency, and supply chain reliability for its customers.

STARTEAM GLOBAL will contribute to and learn from the IPAI community as it continues to explore the opportunities AI can bring to the electronics manufacturing industry.

ISSUE 20 – OCTOBER 2026

NEWS FROM SWEDEN

NCAB Group third-quarter 2026 order intake rose 166% to SEK 2.620 billion and net sales rose 54% to SEK 1.463 billion, with a book-to-bill ratio of 1.79 driven by printed circuit board material shortages and advance orders

Swedish PCB supplier NCAB Group AB reported record results for the third quarter of 2026, with net sales rising 54% year on year to SEK 1.463 billion (approximately US$147.3 million, or RMB 982.1 million) and order intake surging 166% to SEK 2.620 billion (approximately US$263.9 million, or RMB 1.759 billion).

From July to September, organic order intake increased 155% year on year, and the book-to-bill ratio reached 1.79. NCAB estimated that advance orders contributed approximately 80 percentage points to organic order intake growth, while higher prices accounted for around 50 percentage points. Underlying demand was also supported by industrial automation, defence and data center energy infrastructure.

EBITA rose to SEK 210.8 million (approximately US$21.2 million, or RMB 141.5 million) from SEK 110.1 million a year earlier, lifting the EBITA margin to 14.4% from 11.6%. Operating profit increased to SEK 188.7 million, while net profit more than doubled to SEK 129.8 million. Operating cash flow reached SEK 176.8 million.

CEO Peter Kruk said supply-chain pressures intensified during the quarter as heavy data center investment and industrial growth in North America and Europe drove material shortages, longer lead times and higher prices. PCB manufacturers are struggling to secure sufficient raw materials, prompting customers to place orders earlier. NCAB does not expect supply conditions to improve before late 2027 at the earliest.

Kruk said NCAB's scale and long-standing relationships with leading PCB manufacturers help it secure better material allocations and a larger share of production capacity, giving it an advantage in meeting customer demand.

The acquisition of Board Shark PCB, completed in the second quarter, contributed positively to NCAB's U.S. operations. On September 16, 2026, NCAB also signed an agreement to

acquire the business of IMP Electronics Solutions in Adelaide, Australia, expanding its presence in the market.

Despite strong sales growth, gross margin declined slightly because higher purchasing costs had not been fully passed on to customers. Improved productivity and fixed-cost absorption nevertheless boosted profitability.

For the first nine months of 2026, net sales increased 30% year on year to SEK 3.704 billion (approximately US$373.0 million, or RMB 2.487 billion), while order intake climbed 84% to SEK 5.479 billion (approximately US$551.7 million, or RMB 3.678 billion). EBITA rose to SEK 477.6 million (approximately US$48.1 million, or RMB 320.6 million), with the margin improving to 12.9% from 10.7%. Net profit increased to SEK 288.8 million (approximately US$29.1 million, or RMB 193.9 million) from SEK 153.4 million.

NCAB said investments in digitalization and business systems, combined with its strong supplier partnerships, position it to capture further growth amid continued supply-chain constraints.

ISSUE 20 – OCTOBER 2026

NEWS FOM THAILAND

Ventec International Group opened its first Southeast Asian manufacturing facility in Thailand and is investing US$50 million to expand its Kunshan operations in Eastern China

October 26, 2026
Ventec International Group

We're proud to celebrate the grand opening of Ventec International Group's (TWSE: 6672) new manufacturing facility in Thailand, marking our first production base in Southeast Asia and an exciting new chapter in our global growth.

Alongside this milestone, Ventec is investing US$50 million to expand our Kunshan operations in Eastern China, further strengthening our global manufacturing footprint and production capabilities.

These strategic investments reinforce our long-term commitment to supply chain resilience, technological innovation, and meeting the evolving needs of the global electronics industry. With growing opportunities in AI, high-performance computing and advanced electronic materials, we continue to invest in the capabilities and capacity needed to support the next generation of technology.

As we expand our global reach, our focus remains the same: delivering high-performance solutions, reliable supply and trusted support to our customers worldwide.

ISSUE 20 – OCTOBER 2026

NEWS FROM THE USA

Printed Circuit Engineering Association named its 2027-28 Board of Directors, with ASC Sunstone Chief Executive Anaya Vardya as Chairman and Newgrange Design President Matthew Leary as Vice-Chairman

The Printed Circuit Engineering Association (PCEA) have announced its Board of Directors for the 2027-28 term.
Anaya Vardya, CEO of ASC Sunstone, will serve as Chairman, with
Matthew Leary, president of Newgrange Design, becoming Vice-Chairman.
Doug Dixon, chief marketing officer of 360 BC Group, is now Treasurer.
Justin Fleming returns as Secretary

The board sets the strategic direction of the association, which serves the printed circuit board design, fabrication and assembly community through its publications, conferences, and training and certification programs.

Also elected to the PCEA board for 2027-28 are:
Jim Barnes, executive vice president - Global Supply Chain, Generac
Stephen V. Chavez, principal technical product marketing manager, Siemens
Tomas Chester, Founder and hardware designer, Chester Electronic Design
Juan C. Frias, staff PC board designer, Rivian
Rick Hartley, founder, RHartley Enterprises
Charlene McCauley, president, McCauley Design Group
Susy Webb, Senior PCB designer, DesignScience
Eriko Yamato, OEM business development manager, Panasonic
"The board has done a phenomenal job of defining PCEA's mission and path to collaborate, educate and inspire the current and next generation of printed circuit board designers and engineers," said Mike Buetow, president, PCEA. "I am excited for the chance to continue working with them over the next two years.
"I am also grateful to Steph Chavez, our founding chairman, without whom the impressive strides we've made over the past five-plus years would not have been possible."

"PCEA has built something valuable: a place where engineers across the full PCB lifecycle can learn from each other," said Vardya. "As incoming chair, my goal is to build on that foundation by bringing designers and fabricators closer together, supporting the next generation of engineers, and keeping our members ready for what's coming next in electronics."

For more information about PCEA, visit pcea.net.

ISSUE 20 – OCTOBER 2026

PCB TECHNOLOGY NEWS

Artificial intelligence server motherboards became the largest, thickest and most structurally complex printed circuit boards ever manufactured.

October 23, 2026
DIGITIMES

In the era of AI and high-performance computing (HPC), the once-separate worlds of chip design, packaging, and circuit boards are converging. According to the Global Electronics Association, AI server motherboards have become the largest, thickest, and most structurally complex PCBs ever manufactured, drawing substrate and PCB makers, which historically reacted to decisions made by chipmakers and packaging clients, into the heart of AI hardware development.

To identify emerging technology gaps and inform next-generation standards, the association launched its Advanced Electronic Packaging Technology (ADEPT) Committee in North America in April 2025, bringing together more than 25 industry leaders, including IBM, Meta, AMD, Google, and Intel. Taiwan, where critical manufacturing nodes and supply chain partners operate in close physical proximity, has since become the committee's first international satellite.

The committee held its inaugural physical meeting in Taiwan on October 22. In an exclusive interview with DIGITIMES, Matt Kelly (MK), Chief Technology Officer and Vice President of Technology Solutions at the Global Electronics Association, emphasized that in the era of AI and HPC, accelerating convergence across semiconductor packaging, IC substrates, PCBs, and system assembly is elevating the package-to-PCB interface into a critical innovation bottleneck.
Kelly brings more than 25 years of cross-industry expertise and holds 25 patents. He previously spearheaded server and enterprise storage development at IBM and held leadership roles at Celestica and 3M.

Below is an abridged transcript of the interview:
PCBs move to center stage
Q: Before the surge in AI applications, PCBs played a relatively peripheral role and were rarely involved in early-stage chip or system co-design. Why are substrate and PCB manufacturers becoming increasingly vital in the realm of advanced AI packaging?

MK: Looking back 15 to 20 years, the electronics ecosystem operated in distinct silos. The first group comprised silicon wafer fabs, semiconductor IDMs, and chip designers. They led innovation across

design, fabrication, and packaging, giving rise to the famous adage "everything follows silicon," a principle that still holds weight today.

The second group included PCA, PCBA, and end-system manufacturers. Historically, their engagement was passive and downstream: they reacted to decisions dictated by chipmakers and packaging clients, designing components and board layouts after the fact to ensure basic system stability. Today, however, the boundary between these two domains has blurred dramatically. The defining catalyst is that AI server motherboards have become the largest, thickest, and most structurally complex PCBs ever manufactured. Without cutting-edge substrate and PCB fabrication capabilities, supporting next-generation CPUs, GPUs, and custom ASICs operating at peak thermal and electrical thresholds would be impossible, preventing AI systems from functioning as designed.

Furthermore, as the strategic weight of substrate, PCBA, and downstream EMS providers grows, product complexity and manufacturing costs have escalated proportionally. This shift has fundamentally elevated the strategic status of PCB technology within the broader AI ecosystem. Through the ADEPT Committee, the Global Electronics Association is extending a cross-domain integration framework to drive technical expansion and standards development. Rather than relying on traditional, time-consuming passive approaches, we are proactively collaborating across the supply chain during this rapid AI evolution to identify emerging technology gaps, thermal-mechanical challenges, and architectural requirements that will inform next-generation standards and design guidelines.

Taiwan brings speed to the table

Q: ADEPT was established in North America, with Taiwan serving as its first international satellite committee. What key milestones does ADEPT Taiwan aim to achieve? How will cross-border collaboration function across different supply chain segments?

MK: ADEPT was launched in North America in April 2025 and has gathered over 25 industry leaders across OEMs, IDMs, EDA vendors, OSATs, PCB fabricators, and EMS providers, including IBM, Meta, AMD, Google, Intel, HP, ASE, Texas Instruments, NXP, Renesas, and Siemens EDA.

ADEPT Taiwan officially formed in September 2026 and convened its first physical session during the IMPACT Conference, bringing together over 10 leading Taiwanese companies. Discussions focused on advanced packaging standards for AI and HPC, board-level integration hurdles, high-layer-count boards, high-density interconnect (HDI), and substrate-like PCB technologies.

The Taiwan ecosystem's single greatest competitive advantage is speed. Since all critical manufacturing nodes and supply chain partners operate in close physical proximity, Taiwan possesses unparalleled agility in rapid prototyping, technical iteration, reliability testing, and real-time yield optimization. This unique clustering is precisely why Taiwan remains the irreplaceable hardware anchor of global AI development.

For participating companies, ADEPT Taiwan serves as an international dialogue platform bridging major North American tech giants with Taiwan's localized manufacturing ecosystem. This synergy reinforces dual leadership in global AI hardware, accelerates commercial adoption of emerging packaging standards, and fosters a more resilient supply chain.

However, the association does not operate top-down. In these early stages, our primary mission is to listen to the operational needs of global ADEPT members and build consensus through white papers, unified guidelines, industry standards, and technical training.

Navigating this process comes with inherent challenges, particularly regarding proprietary IP that companies cannot disclose. When drafting industry standards, the committee first establishes clear boundaries to safeguard proprietary domain data, allowing members to focus on solving baseline pain points and identifying the "greatest common denominator" across materials, design rules, manufacturing processes, and testing methodologies

News from
WECC members

WECC
World Electronic Circuits Council

Issue 20 - October 2026

NEWS FROM THE TPCA

Taiwan printed circuit board industry output was expected to exceed NT$1 trillion for the first time in 2026, reaching NT$1.1365 trillion, up 24.2%; first-half 2026 output rose 23.9% to NT$524.7 billion - Taiwan Printed Circuit Association

The 27th Taiwan Printed Circuit Industry International Exhibition (TPCA Show 2026) opened in Nangang on October 20, with Vice President Hsiao Bi-khim calling on the PCB industry to seize opportunities created by the AI boom.

Taiwan's PCB industry is expected to generate more than NT$1 trillion in output for the first time in 2026 as AI infrastructure drives demand across the technology supply chain.
Hsiao said that as AI transforms global technology, every breakthrough - from semiconductors, advanced packaging and data centres to high-performance computing - requires reliable technical support from the PCB industry. Taiwan's PCB sector has the capacity to generate trillion-dollar output and plays a critical role in the global supply chain.

Shortages spread as output climbs
According to data from the Taiwan Printed Circuit Association (TPCA), rapidly expanding demand for AI infrastructure has extended growth from PCB manufacturing upstream to materials and equipment suppliers.

Since the second half of 2025, supply and demand for PCBs, substrates and key materials have tightened. Material shortages have not eased in 2026; instead, their impact has gradually expanded from high-end materials to copper-clad laminates (CCL) and ABF substrates.

TPCA said domestic and overseas output reached NT$524.7 billion (US$16.18 billion) in the first half of 2026, up 23.9% year-over-year. Full-year output is expected to exceed NT$1 trillion for the first time, reaching NT$1.1365 trillion, an annual increase of 24.2%.

Cross-industry push for AI
Hsiao said Taiwan has international competitive advantages in both semiconductors and PCBs. Close cooperation between the two industries is not only key to Taiwan's ability to capitalize on AI, but also an important foundation for advancing the Five Trusted Industry Sectors.

She said Taiwan should use technological complementarity and cross-industry integration to maximize the strength of its high-tech industries, jointly capture new AI opportunities and expand its lead in high-end global manufacturing.

TPCA Chairman Chang Yuan-ming said the pace of AI development is rewriting the rules of the electronics supply chain. Facing the historic opportunity created by AI, Taiwan's PCB industry is no longer merely a manufacturer but also a co-definer of AI hardware specifications and a key partner.

Hsiao said Taiwan must respond to the global technological transformation driven by AI by combining complementary technologies and integrating industries to build an innovative and resilient industrial ecosystem. The government will continue strengthening foundational resources, including energy, water and talent, to help upgrade the industry supply chain and serve as the sector's strongest support.

International Diary

2026

EIPC @ Electronica 2026
10-13 November
Munchen, Germany

FED Austrian Electronics Day
26 November
Dornbirn, Austria

HKPCA
2-4 December
Shenzhen, Hong Kong

2027

EIPC Winter Conference
February

EIPC Summer Conference
8 & 9 June

Electronics Manufacturing & Packaging Symposium (EMPS)
28 June-1 July
ESA/ESTEC Noordwijk, NL

ECWC17 Electronics Circuit World Convention
18-20 August
Bangkok, Thailand